

FLASH MEMORY

CMOS

4M (512K × 8) BIT

MBM29F040A-90-X/-12-X

■ FEATURES

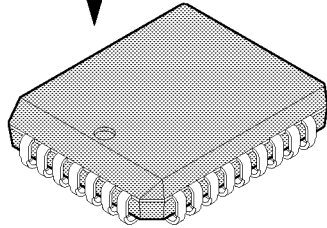
- **Single 5.0 V read, write, and erase**
Minimizes system level power requirements
- **Compatible with JEDEC-standard commands**
Uses same software commands as E²PROMs
- **Compatible with JEDEC-standard byte-wide pinouts**
32-pin PLCC (Package suffix: PD)
32-pin TSOP (Package suffix: PFTN – Normal Bend Type, PFTR – Reversed Bend Type)
- **Minimum 100,000 write/erase cycles**
- **High performance**
90 ns maximum access time
- **Sector erase architecture**
8 equal size sectors of 64 K bytes each
Any combination of sectors can be concurrently erased. Also supports full chip erase.
- **Embedded Erase™ Algorithms**
Automatically pre-programs and erases the chip or any sector
- **Embedded Program™ Algorithms**
Automatically writes and verifies data at specified address
- **Data Polling and Toggle Bit feature for detection of program or erase cycle completion**
- **Low V_{cc} write inhibit ≤3.2 V**
- **Sector protection**
Hardware method disables any combination of sectors from write or erase operations
- **Erase Suspend/Resume**
Suspends the erase operation to allow a read data in another sector within the same device
- **Extended operating temperature range: –40°C to +85°C**

Please refer to “MBM29F040A-70/-90/-12” in detailed specifications.

MBM29F040A-90-X/-12-X

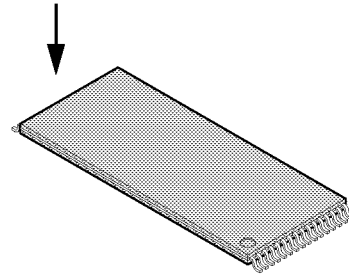
■ PACKAGE

Marking Side

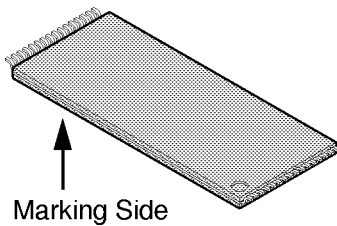


32-pin Plastic LCC
(LCC-32P-M02)

Marking Side



32-pin Plastic TSOP
(FPT-32P-M24 — Assembly: Malaysia)



32-pin Plastic TSOP
(FPT-32P-M25 — Assembly: Malaysia)

■ GENERAL DESCRIPTION

The MBM29F040A-X is a 4 M-bit, 5.0 V-only Flash memory organized as 512 K bytes of 8 bits each. The MBM29F040A-X is offered in a 32-pin PLCC and 32-pin TSOP packages. This device is designed to be programmed in-system with the standard system 5.0 V V_{CC} supply. A 12.0 V V_{PP} is not required for write or erase operations. The device can also be reprogrammed in standard EPROM programmers.

The industrial MBM29F040A-X offers access times of 90 ns and 120 ns, allowing operation of high-speed microprocessors without wait states. To eliminate bus contention the device has separate chip enable (\overline{CE}), write enable (\overline{WE}), and output enable (\overline{OE}) controls.

The MBM29F040A-X is pin and command set compatible with JEDEC standard 4 M-bit E²PROMs. Commands are written to the command register using standard microprocessor write timings. Register contents serve as input to an internal state-machine which controls the erase and programming circuitry. Write cycles also internally latch addresses and data needed for the programming and erase operations. Reading data out of the device is similar to reading from 12.0 V Flash or EPROM devices.

The MBM29F040A-X is programmed by executing the program command sequence. This will invoke the Embedded Program Algorithm which is an internal algorithm that automatically times the program pulse widths and verifies proper cell margin. Typically, each sector can be programmed and verified in less than 0.5 seconds. Erase is accomplished by executing the erase command sequence. This will invoke the Embedded Erase Algorithm which is an internal algorithm that automatically preprograms the array if it is not already programmed before executing the erase operation. During erase, the device automatically times the erase pulse widths and verifies proper cell margin.

A sector is typically erased and verified in 1.0 second (if already completely preprogrammed).

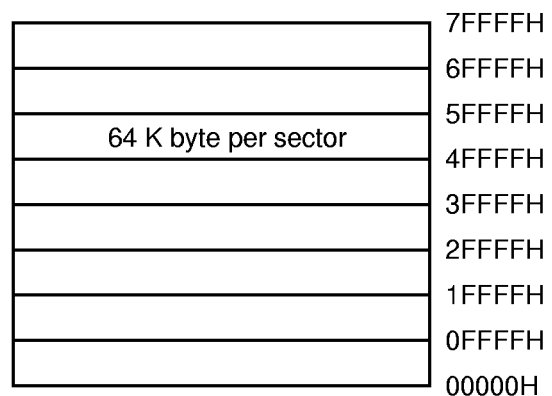
This device also features a sector erase architecture. The sector mode allows for 64 K byte sectors of memory to be erased and reprogrammed without affecting other sectors. The MBM29F040A-X is erased when shipped from the factory.

The device features single 5.0 V power supply operation for both read and write functions. Internally generated and regulated voltages are provided for the program and erase operations. A low V_{CC} detector automatically inhibits write operations on the loss of power. The end of program or erase is detected by \overline{Data} Polling of DQ₇ or by the Toggle Bit feature on DQ₆. Once the end of a program or erase cycle has been completed, the device internally resets to the read mode.

Fujitsu's Flash technology combines years of EPROM and E²PROM experience to produce the highest levels of quality, reliability and cost effectiveness. The MBM29F040A-X memory electrically erases the entire chip or all bits within a sector simultaneously via Fowler-Nordhiem tunneling. The bytes are programmed one byte at a time using the EPROM programming mechanism of hot electron injection.

FLEXIBLE SECTOR-ERASE ARCHITECTURE

- 64 K byte per sector
- Individual-sector, multiple-sector, or bulk-erase capability
- Individual or multiple-sector protection is user definable

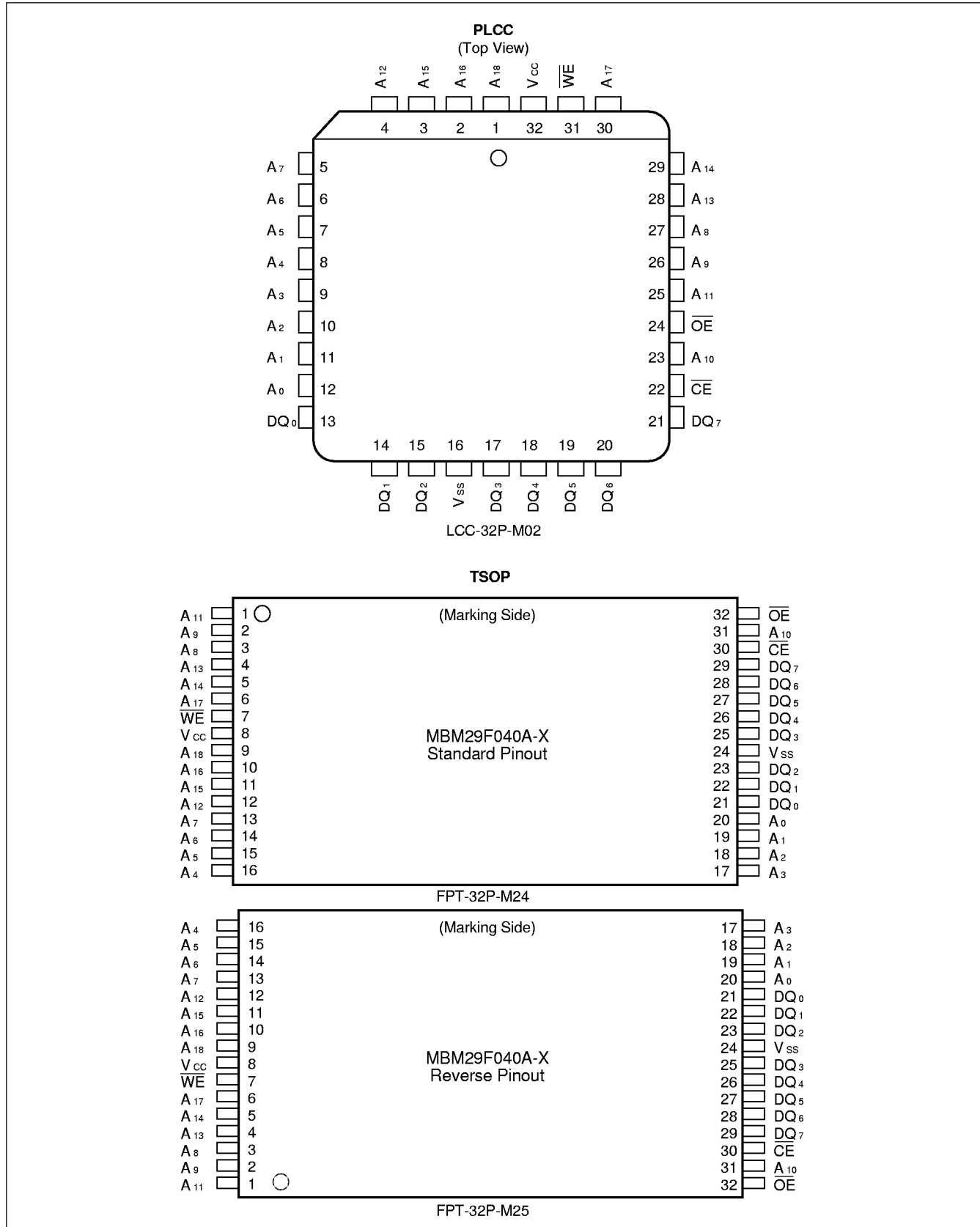


MBM29F040A-90-X/-12-X

■ PRODUCT SELECTOR GUIDE

Part No.	MBM29F040A	
Ordering Part No.	-90-X	-12-X
Max. Address Access Time (ns)	90	120
Max. \overline{CE} Access Time (ns)	90	120
Max. \overline{OE} Access Time (ns)	35	50

CONNECTION DIAGRAMS



MBM29F040A-90-X/-12-X

■ LOGIC SYMBOL

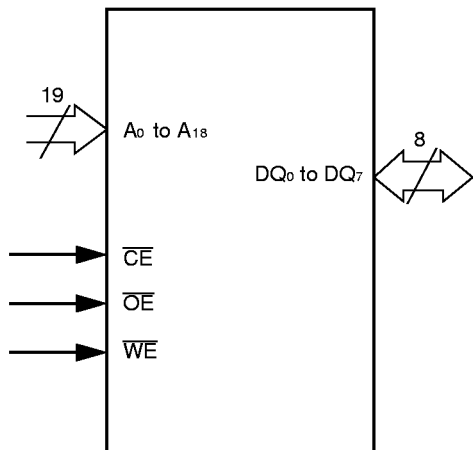


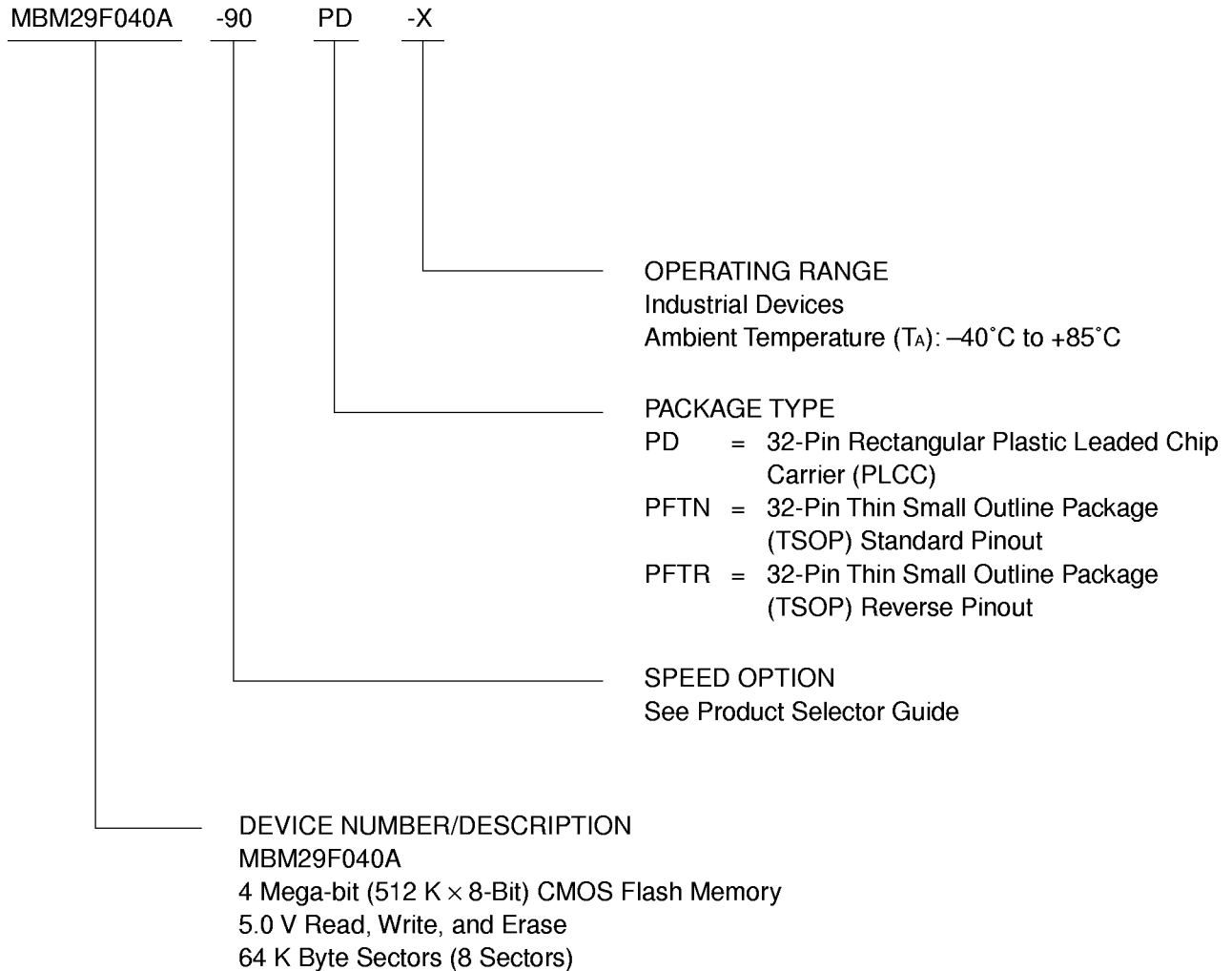
Table 1 MBM29F040A Pin Configuration

Pin	Function
A ₀ to A ₁₈	Address Inputs
DQ ₀ to DQ ₇	Data Inputs/Outputs
\overline{CE}	Chip Enable
\overline{OE}	Output Enable
\overline{WE}	Write Enable
V _{SS}	Device Ground
V _{CC}	Device Power Supply (5.0 V \pm 10%)

■ ORDERING INFORMATION

Industrial Devices

Fujitsu industrial devices are available in several packages. The order number is formed by a combination of:



MBM29F040A-90-X/-12-X

■ ABSOLUTE MAXIMUM RATINGS

Storage Temperature	-55°C to +125°C
Ambient Temperature with Power Applied	-40°C to +85°C
Voltage with Respect to Ground All pins except A ₉ , \overline{OE} (Note 1)	-2.0 V to +7.0 V
V _{CC} (Note 1)	-2.0 V to +7.0 V
A ₉ , \overline{OE} (Note 2)	-2.0 V to +13.5 V

- Notes: 1. Minimum DC voltage on input or I/O pins are -0.5 V. During voltage transitions, inputs may negative overshoot V_{SS} to -2.0 V for periods of up to 20 ns. Maximum DC voltage on output and I/O pins is V_{CC} +0.5 V. During voltage transitions, outputs may positive overshoot to V_{CC} +2.0 V for periods of up to 20 ns.
2. Minimum DC input voltage on A₉, \overline{OE} pins are -0.5 V. During voltage transitions, A₉, and \overline{OE} pins may negative overshoot V_{SS} to -2.0 V for periods of up to 20 ns. Maximum DC input voltage on A₉, and \overline{OE} are +13.5 V which may overshoot to 14.0 V for periods of up to 20 ns.

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

■ RECOMMENDED OPERATING RANGES

Industrial Devices

Ambient Temperature (T _A)	-40°C to +85°C
V _{CC} Supply Voltages	+4.50 V to +5.50 V

Operating ranges define those limits between which the functionality of the device is guaranteed.

WARNING: Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their FUJITSU representative beforehand.

■ MAXIMUM OVERSHOOT

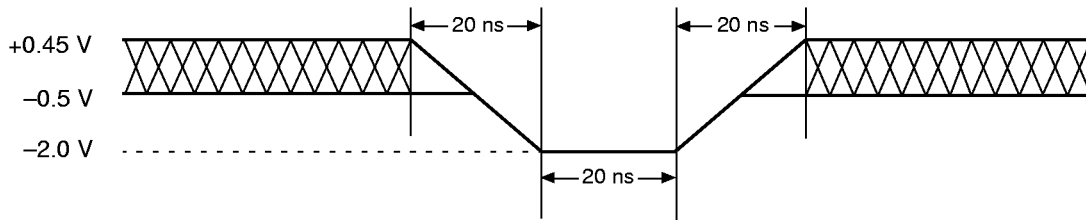


Figure 1 Maximum Negative Overshoot Waveform

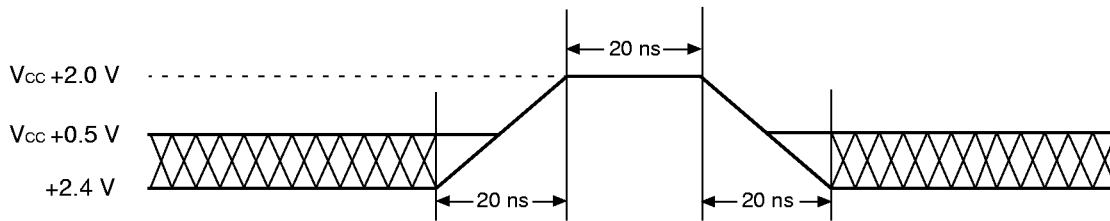
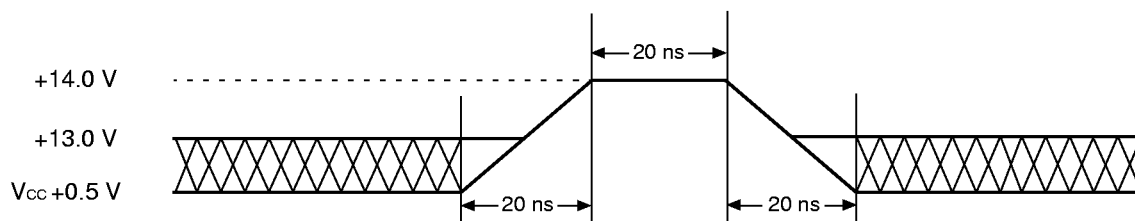


Figure 2 Maximum Positive Overshoot Waveform



* : This waveform is applied for A_9 and \overline{OE} .

Figure 3 Maximum Positive Overshoot Waveform

MBM29F040A-90-X/-12-X

■ DC CHARACTERISTICS

TTL/NMOS Compatible

Parameter Symbol	Parameter Description	Test Conditions	Min.	Max.	Unit
I_{LI}	Input Leakage Current	$V_{IN} = V_{SS}$ to V_{CC} , $V_{CC} = V_{CC}$ Max.	—	± 1.0	μA
I_{LO}	Output Leakage Current	$V_{OUT} = V_{SS}$ to V_{CC} , $V_{CC} = V_{CC}$ Max.	—	± 1.0	μA
I_{LIT}	A_9 , \overline{OE} Inputs Leakage Current	$V_{CC} = V_{CC}$ Max. A_9 , $\overline{OE} = 12.0$ V	—	50	μA
I_{CC1}	V_{CC} Active Current (Note 1)	$\overline{CE} = V_{IL}$, $\overline{OE} = V_{IH}$	—	50	mA
I_{CC2}	V_{CC} Active Current (Note 2)	$\overline{CE} = V_{IL}$, $\overline{OE} = V_{IH}$	—	80	mA
I_{CC3}	V_{CC} Standby Current	$V_{CC} = V_{CC}$ Max., $\overline{CE} = V_{IH}$	—	1.5	mA
V_{IL}	Input Low Level	—	-0.5	0.45	V
V_{IH}	Input High Level	—	2.4	$V_{CC} + 0.5$	V
V_{ID}	Voltage for Autoselect and Sector Protection (A_9 , \overline{OE})	$V_{CC} = 5.0$ V	11.5	12.5	V
V_{OL}	Output Low Voltage Level	$I_{OL} = 12$ mA, $V_{CC} = V_{CC}$ Min.	—	0.45	V
V_{OH}	Output High Voltage Level	$I_{OH} = -2.5$ mA, $V_{CC} = V_{CC}$ Min.	2.4	—	V
V_{LKO}	Low V_{CC} Lock-Out Voltage	—	3.2	4.2	V

Notes: 1. The I_{CC} current listed includes both the DC operating current and the frequency dependent component (at 6 MHz).

The frequency component typically is 2 mA/MHz, with \overline{OE} at V_{IH} .

2. I_{CC} active while Embedded Algorithm (program or erase) is in progress.

MBM29F040A-90-X/-12-X

CMOS Compatible

Parameter Symbol	Parameter Description	Test Conditions	Min.	Max.	Unit
I _{LI}	Input Leakage Current	V _{IN} = V _{SS} to V _{CC} , V _{CC} = V _{CC} Max.	—	±1.0	μA
I _{LO}	Output Leakage Current	V _{OUT} = V _{SS} to V _{CC} , V _{CC} = V _{CC} Max.	—	±1.0	μA
I _{LIT}	A ₉ , \overline{OE} Inputs Leakage Current	V _{CC} = V _{CC} Max. A ₉ , \overline{OE} = 12.0 V	—	50	μA
I _{CC1}	V _{CC} Active Current (Note 1)	\overline{CE} = V _{IL} , \overline{OE} = V _{IH}	—	50	mA
I _{CC2}	V _{CC} Active Current (Note 2)	\overline{CE} = V _{IL} , \overline{OE} = V _{IH}	—	80	mA
I _{CC3}	V _{CC} Standby Current	V _{CC} = V _{CC} Max., \overline{CE} = V _{CC} ±0.3 V	—	100	μA
V _{IL}	Input Low Level	—	-0.5	0.45	V
V _{IH}	Input High Level	—	0.7×V _{CC}	V _{CC} +0.3	V
V _{ID}	Voltage for Autoselect and Sector Protection (A ₉ , \overline{OE})	V _{CC} = 5.0 V	11.5	12.5	V
V _{OL}	Output Low Voltage Level	I _{OL} = 12.0 mA, V _{CC} = V _{CC} Min.	—	0.45	V
V _{OH1}	Output High Voltage Level	I _{OH} = -2.5 mA, V _{CC} = V _{CC} Min.	0.85×V _{CC}	—	V
V _{OH2}		I _{OH} = -100 μA, V _{CC} = V _{CC} Min.	V _{CC} -0.4	—	V
V _{LKO}	Low V _{CC} Lock-Out Voltage	—	3.2	4.2	V

Notes: 1. The I_{CC} current listed includes both the DC operating current and the frequency dependent component (at 6 MHz).

The frequency component typically is 2 mA/MHz, with \overline{OE} at V_{IH}.

2. I_{CC} active while Embedded Algorithm (program or erase) is in progress.

MBM29F040A-90-X/-12-X

AC CHARACTERISTICS

Read Only Operations Characteristics

Parameter Symbols		Description	Test Set Up		-90-X (Note)	-12-X (Note)	Unit
JEDEC	Standard						
t_{AVAV}	t_{RC}	Read Cycle Time	—	Min.	90	120	ns
t_{AVQV}	t_{ACC}	Address to Output Delay	$\overline{CE} = V_{IL}$ $\overline{OE} = V_{IL}$	Max.	90	120	ns
t_{ELQV}	t_{CE}	Chip Enable to Output Delay	$\overline{OE} = V_{IL}$	Max.	90	120	ns
t_{GLQV}	t_{OE}	Output Enable to Output Delay	—	Max.	35	50	ns
t_{EHQZ}	t_{DF}	Chip Enable to Output High-Z	—	Max.	20	30	ns
t_{GHQZ}	t_{DF}	Output Enable to Output High-Z	—	Max.	20	30	ns
t_{AXQX}	t_{OH}	Output Hold Time From Addresses, \overline{CE} or \overline{OE} , Whichever Occurs First	—	Min.	0	0	ns

Note: Test Conditions: Output Load: 1 TTL gate and 100 pF
 Input rise and fall times: 20 ns
 Input pulse levels: 0.0 V to 3.0 V
 Timing measurement reference level
 Input: 0.45 V and 2.4 V
 Output: 0.8 V and 2.0 V

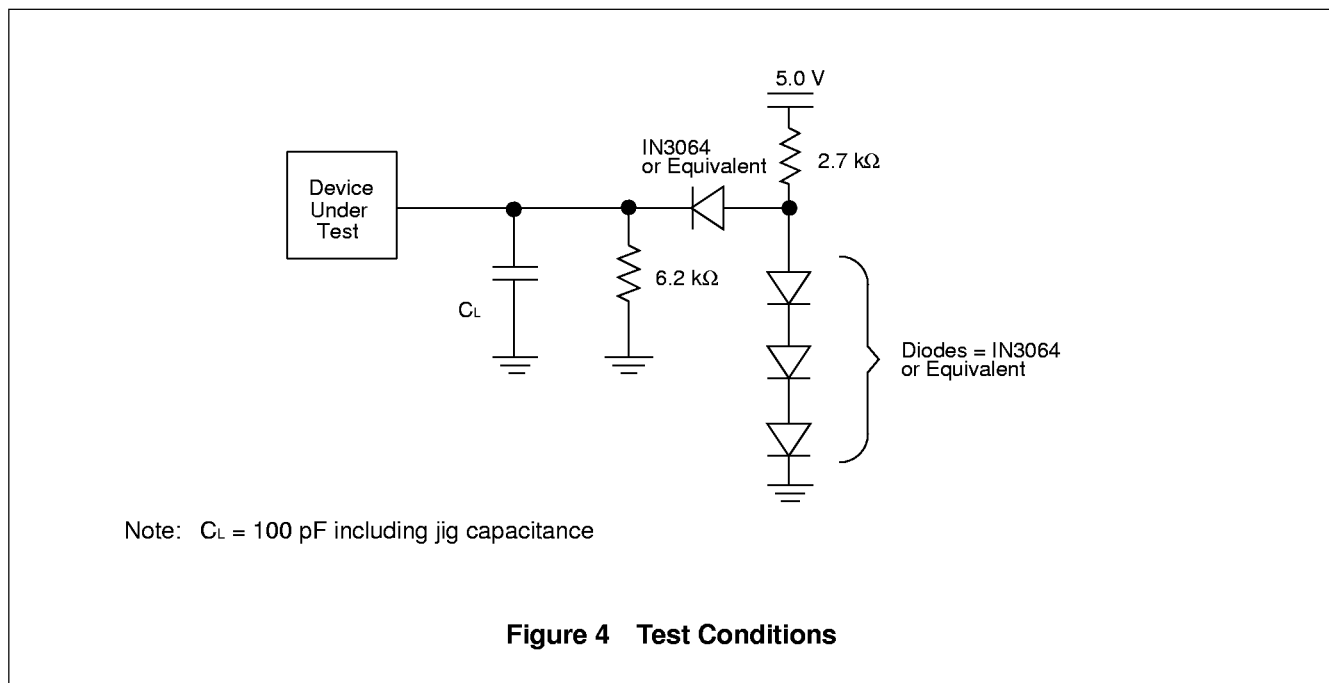


Figure 4 Test Conditions

MBM29F040A-90-X/-12-X

- Write/Erase/Program Operations
Alternate WE Controlled Writes

Parameter Symbols		Description		-90-X	-12-X	Unit
JEDEC	Standard					
t _{AVAV}	t _{WC}	Write Cycle Time	Min.	90	120	ns
t _{AVWL}	t _{AS}	Address Set Up Time	Min.	0	0	ns
t _{WLAX}	t _{AH}	Address Hold Time	Min.	45	50	ns
t _{DVWH}	t _{DS}	Data Set Up Time	Min.	45	50	ns
t _{WHDX}	t _{DH}	Data Hold Time	Min.	0	0	ns
—	t _{OES}	Output Enable Set Up Time	Min.	0	0	ns
—	t _{OEH}	Output Enable Hold Time	Read	Min.	0	ns
			Toggle and $\overline{\text{Data}}$ Polling	Min.	10	ns
t _{GHWL}	t _{GHWL}	Read Recover Time Before Write	Min.	0	0	ns
t _{ELWL}	t _{CS}	$\overline{\text{CE}}$ Set Up Time	Min.	0	0	ns
t _{WHEH}	t _{CH}	$\overline{\text{CE}}$ Hold Time	Min.	0	0	ns
t _{WLWH}	t _{WP}	Write Pulse Width	Min.	45	50	ns
t _{WHWL}	t _{WPH}	Write Pulse Width High	Min.	20	20	ns
t _{WHWH1}	t _{WHWH1}	Byte Programming Operation	Typ.	16	16	μs
t _{WHWH2}	t _{WHWH2}	Sector Erase Operation (Note 1)	Typ.	1.5	1.5	sec
			Max.	30	30	sec
—	t _{VCS}	V _{CC} Set Up Time	Min.	50	50	μs
—	t _{VLHT}	Voltage Transition Time (Note 2)	Min.	4	4	μs
—	t _{WPP}	Write Pulse Width (Note 2)	Min.	100	100	μs
—	t _{OESP}	$\overline{\text{OE}}$ Set Up Time to $\overline{\text{WE}}$ Active (Note 2)	Min.	4	4	μs
—	t _{CSP}	$\overline{\text{CE}}$ Set Up Time to $\overline{\text{WE}}$ Active (Note 2)	Min.	4	4	μs

Notes: 1. This does not include the preprogramming time.

2. This timing is for Sector Protection operation.

MBM29F040A-90-X/-12-X

- Write/Erase/Program Operations
Alternate CE Controlled Writes

Parameter Symbols		Description		-90-X	-12-X	Unit
JEDEC	Standard					
t _{AVAV}	t _{WC}	Write Cycle Time	Min.	90	120	ns
t _{AVEL}	t _{AS}	Address Set Up Time	Min.	0	0	ns
t _{ELAX}	t _{AH}	Address Hold Time	Min.	45	50	ns
t _{DVEH}	t _{DS}	Data Set Up Time	Min.	45	50	ns
t _{EHDX}	t _{DH}	Data Hold Time	Min.	0	0	ns
—	t _{OES}	Output Enable Set Up Time	Min.	0	0	ns
—	t _{OEHL}	Output Enable Hold Time	Read	Min.	0	ns
			Toggle and Data Polling	Min.	10	ns
t _{GHEL}	t _{GHEL}	Read Recover Time Before Write	Min.	0	0	ns
t _{WLEL}	t _{WS}	\overline{WE} Set Up Time	Min.	0	0	ns
t _{EHWH}	t _{WH}	\overline{WE} Hold Time	Min.	0	0	ns
t _{ELEH}	t _{CP}	\overline{CE} Pulse Width	Min.	45	50	ns
t _{EHEL}	t _{CPH}	\overline{CE} Pulse Width High	Min.	20	20	ns
t _{WHWH1}	t _{WHWH1}	Byte Programming Operation	Typ.	16	16	μs
t _{WHWH2}	t _{WHWH2}	Sector Erase Operation (Note)	Typ.	1.5	1.5	sec
			Max.	30	30	sec
—	t _{VCS}	V _{CC} Set Up Time	Min.	50	50	μs

Note: This does not include the preprogramming time.

■ ERASE AND PROGRAMMING PERFORMANCE

Parameter	Limits			Unit	Comments
	Min.	Typ.	Max.		
Sector Erase Time	—	1.5	30	sec	Excludes 00H programming prior to erasure
Byte Programming Time	—	8	500	μs	Excludes system-level overhead
Chip Programming Time	—	8.5	50	sec	Excludes system-level overhead
Erase/Program Cycle	100,000	—	—	cycles	

■ TSOP PIN CAPACITANCE

Parameter Symbol	Parameter Description	Test Setup	Typ.	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0	7	8	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0	8	10	pF
C _{IN2}	Control Pin Capacitance	V _{IN} = 0	8.5	10	pF

Note: Test conditions T_A = 25°C, f = 1.0 MHz

■ PLCC PIN CAPACITANCE

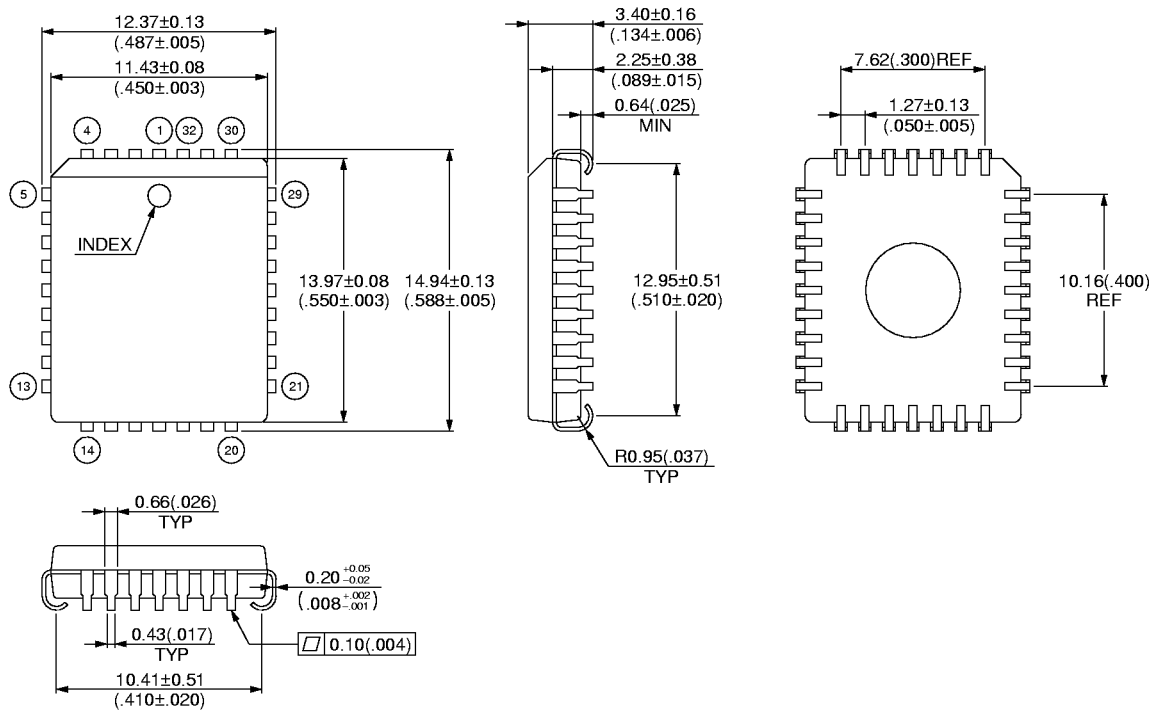
Parameter Symbol	Parameter Description	Test Setup	Typ.	Max.	Unit
C _{IN}	Input Capacitance	V _{IN} = 0	7	8	pF
C _{OUT}	Output Capacitance	V _{OUT} = 0	8	10	pF
C _{IN2}	Control Pin Capacitance	V _{IN} = 0	8.5	10	pF

Note: Test conditions T_A = 25°C, f = 1.0 MHz

MBM29F040A-90-X/-12-X

■ PACKAGE DIMENSIONS

32-Pin Plastic LCC
(LCC-32P-M02)

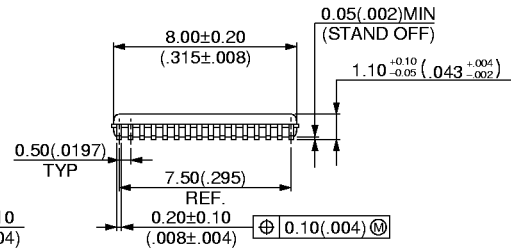
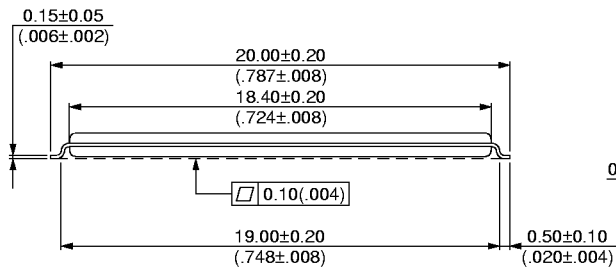
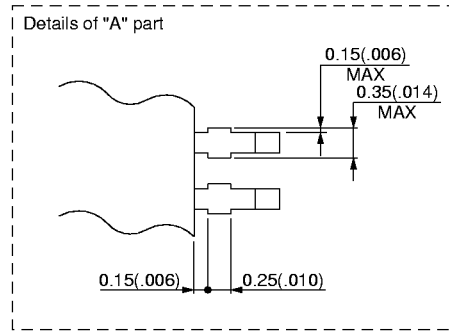
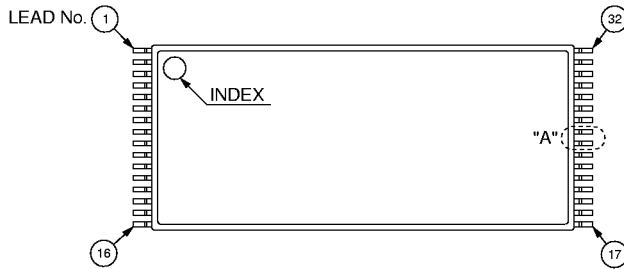


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Dimensions in mm(inches)

MBM29F040A-90-X/-12-X

32-Pin Plastic TSOP
(FPT-32P-M24 — Assembly: Malaysia)

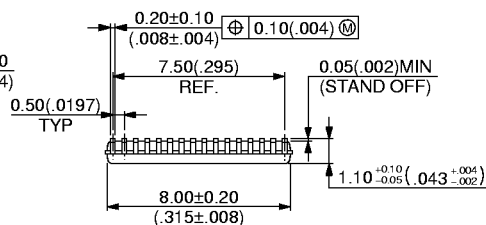
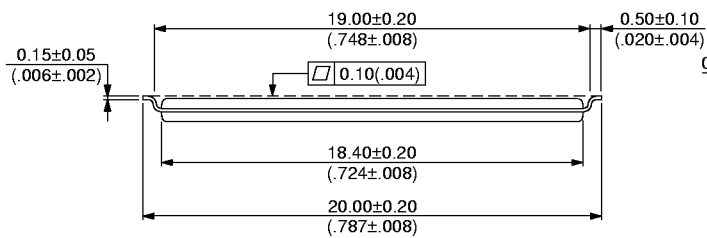
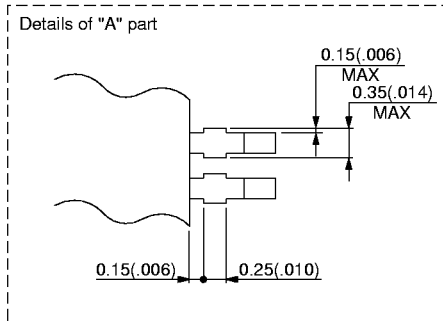
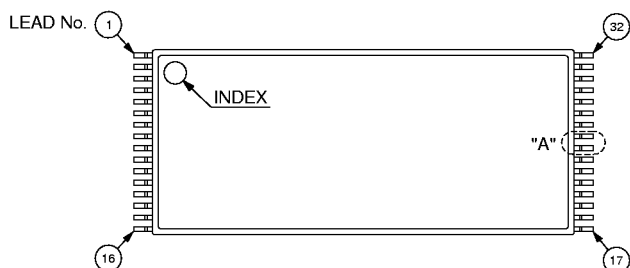


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Dimensions in mm(inches)

MBM29F040A-90-X/-12-X

32-Pin Plastic TSOP
(FPT-32P-M25 — Assembly: Malaysia)



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Dimensions in mm(inches)